


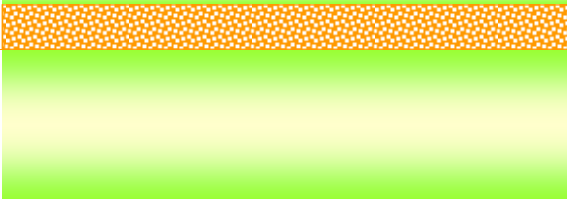

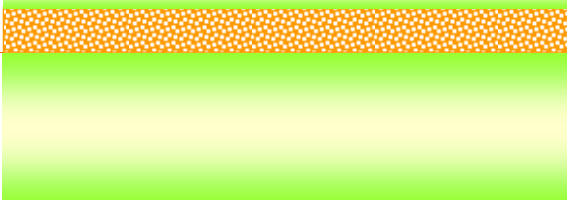


Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly		
Layer-1	35 μ	Copper		A1		
	60 μ	Prepreg				
	60 μ	Prepreg				
Layer-2	35 μ	Copper			B	
	610 μ	L-FR4				
Layer-3	35 μ	Copper				A2
	60 μ	Prepreg				
	60 μ	Prepreg				
Layer-4	35 μ	Copper				
	610 μ	L-FR4				
Layer-5	35 μ	Copper		B		
	60 μ	Prepreg				
	60 μ	Prepreg				
Layer-99	35 μ	Copper				

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